CLAIMS

1. A conductive adhesive comprising the following components (A) to (C), the conductive adhesive being liquid at 25°C:

component (A): an alicyclic epoxy resin;

component (B): a boron-based thermal cationic initiator; and

component (C): a conductive filler,

wherein the component (C) contains a conductive filler (C-1) having a 50% average particle diameter of 3 μm or more and a conductive filler (C-2) having a 50% average particle diameter of less than 3 μm and a ratio of a mass of the component (C-1) to a mass of the component (C-2) is 0.01 to 30.

2. The conductive adhesive according to claim 1, wherein the component (B) contains a salt of a quaternary ammonium cation and a borate anion.

3. The conductive adhesive according to claim 1 or 2, wherein the component (B) contains at least either of a salt of a quaternary ammonium cation and a tetrafluoroborate anion or a salt of a quaternary ammonium cation and a tetrakis(pentafluorophenyl)borate anion.

4. The conductive adhesive according to any one of claims 1 to 3, wherein at least one of the component (C-1) or the component (C-2) has a surface treated with a lubricant.

5. The conductive adhesive according to any one of claims 1 to 4, wherein the component (A) is an alicyclic epoxy resin having two or more epoxy groups in one molecule.

6. The conductive adhesive according to any one of claims 1 to 5, wherein a tap density of each conductive filler as the component (C) is 0.1 to 100 g/cm^3.

7. The conductive adhesive according to any one of claims 1 to 6, wherein the component (C) has a plurality of shapes.

8. The conductive adhesive according to any one of claims 1 to 7, wherein the component (B) is contained at 0.1 to 30 parts by mass with respect to 100 parts by mass of the component (A).

9. The conductive adhesive according to any one of claims 1 to 8, wherein the component (B) is contained at 1 to 20 parts by mass with respect to 100 parts by mass of the component (A).

10. The conductive adhesive according to any one of claims 1 to 9, which is used for an adherend containing polycarbonate.

11. A cured product of the conductive adhesive set forth in any one of claims 1 to 10.